

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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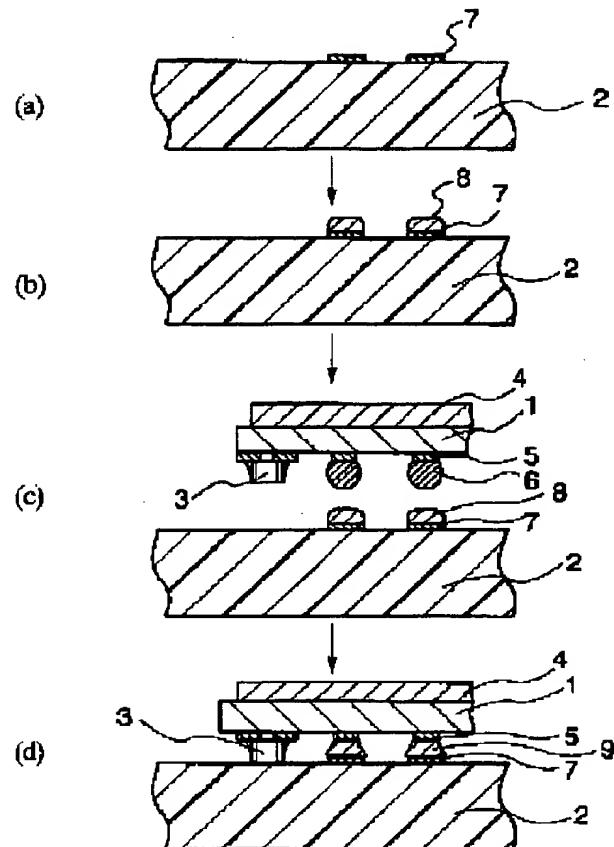
APPLICATION DATE : 27-10-95  
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APPLICANT : HITACHI INF TECHNOL:KK;

INVENTOR : SAKAGAMI MASAKAZU;

INT.CL. : H05K 3/34 H05K 1/18

TITLE : MOUNTING OF ELECTRONIC PARTS



**ABSTRACT :** PROBLEM TO BE SOLVED: To form the shape of a bump to a drum type from a column type to improve connection reliability of the connecting portion by preventing crushing of excessive bump of solder bump to control the height of bump.

SOLUTION: In the mounting structure depending on the method where an electronic part 1 is mounted on the mounting substrate 2 via the solder bump 6 provided on the electronic part 1, an electronic part 1 of the surface mounting type, a printed circuit board 2 for mounting the electronic part 1 and a chip type part 3 provided to the electronic part 1 are comprised and the solder bump 6 which is to be fused and crushed by the weight of the electronic part 1 is supported by a chip type part 3 when the electronic part 1 is to be soldered to the printed circuit board 2. Thereby, the solder bump 6 is formed in the shape of the column or drum like a connection bump 9 and size of gap between the electronic part 1 and printed circuit board 2 is determined by the height of the chip type part 3.

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(21)Application number : **07-279537**

(71)Applicant : **HITACHI LTD  
HITACHI INF TECHNOL:KK**

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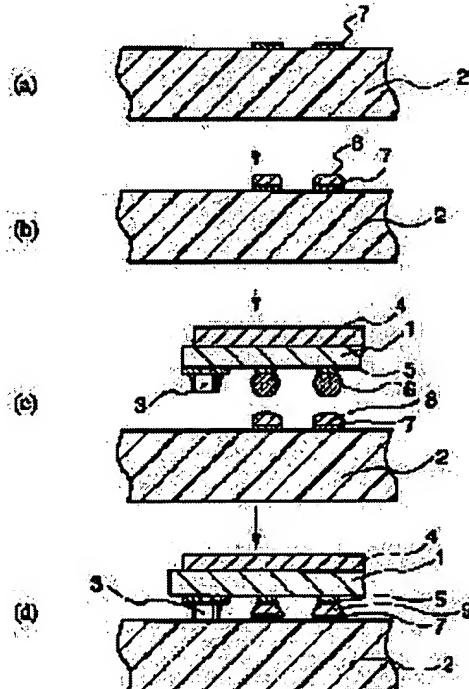
(72)Inventor : **ITO HIROSHI  
KAMIMURA YASUHIRO  
SAKAGAMI MASAKAZU**

## **(54) MOUNTING OF ELECTRONIC PARTS**

### **(57)Abstract:**

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**SOLUTION:** In the mounting structure depending on the method where an electronic part 1 is mounted on the mounting substrate 2 via the solder bump 6 provided on the electronic part 1, an electronic part 1 of the surface mounting type, a printed circuit board 2 for mounting the electronic part 1 and a chip type part 3 provided to the electronic part 1 are comprised and the solder bump 6 which is to be fused and crushed by the weight of the electronic part 1 is supported by a chip type part 3 when the electronic part 1 is to be soldered to the printed circuit board 2. Thereby, the solder bump 6 is formed in the shape of the column or drum like a connection bump 9 and size of gap between the electronic part 1 and printed circuit board 2 is determined by the height of the chip type part 3.



## **LEGAL STATUS**

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